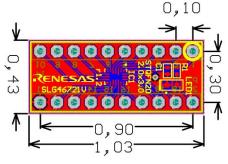


1. Description

The GreenPAK DIP Adapter is a small PCB that lets you adapt STQFN packages into a DIP footprint. This board can speed up your design prototyping and testing. This small board 0.43x1.03 inch uses 20 pins DIP footprint with 0.3 inch width. You can also use this adapter for prototyping by making STQFN package compatible with solder free breadboards.

2. Features

- Low cost •
- Simplifies prototyping of SMT IC's •
- Optional V_{DD} LED indicator •
- Decoupling capacitor included



Note 1 All sizes in inches.

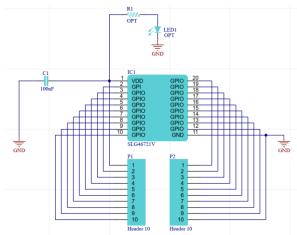
4. Bottom View

Chi		
Pins		Pins
PIN20 (GPIO)		PIN1 (VDD)
PIN19 (GPIO)		PIN2 (GPI)
PIN18 (GPIO)	🗖 🖬 🚓 🛛 🗖	PIN3 (GPIO)
PIN17 (GPIO)		PIN4 (GPIO)
PIN16 (GPIO)		PIN5 (GPIO)
PIN15 (GPIO)		PIN6 (GPIO)
PIN14 (GPIO)		PIN7 (GPIO)
PIN13 (GPIO)		PIN8 (GPIO
PIN12 (GPIO)		PIN9 (GPIO)
PIN11 (GND)		PIN10 (GPIO)

3. Top View

LED current limit res	istor (optional)	Chip package	type
VDD Chip decouplin	g capacitor	VDD LED in	ndicator (optional)
Pins			Pins
PIN1 (VDD)		LEDI	PIN20 (GPIO)
PIN2 (GPI)	0	G	PIN19 (GPIO)
PIN3 (GPIO)	- 🔁 CI	G	PIN18 (GPIO)
PIN4 (GPIO)		FN20 x3.0 🕞	PIN17 (GPIO)
PIN5 (GPIO)	- O • F		PIN16 (GPIO)
PIN6 (GPIO)	91		PIN15 (GPIO)
PIN7 (GPIO)	O	ÿ ² _ <mark>©</mark>	PIN14 (GPIO)
PIN8 (GPIO)	-0	N 2 0	PIN13 (GPIO)
PIN9 (GPIO)	-0	Ž 2 0	PIN12 (GPIO)
PIN10 (GPIO)	9		PIN11 (GND)
Greer	PAK chip	Chir	part number

5. Board Schematic



Revision 1.1

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